

CYStech Electronics Corp.

Spec. No.: C327SA Issued Date: 2003.04.04

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CSMA400XSA Series

1.0Amp. Surface Mount Glass Passivated Type Rectifiers

Features

- For surface mounted application
- Low forward voltage drop and low leakage current
- High current capability
- Easy pick and place
- High surge current capability
- Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0 Utilizing Flame Retardant Epoxy Molding Compound.
- High temperature soldering: 250°C/10 seconds at terminals
- Exceeds environmental standards of MIL-S-19500/228

Mechanical Data

- Case: SMA/DO-214AC Molded Plastic.
- Terminals: Solder plated. Solderable per MIL-STD-750 Method
- Polarity: Indicated by cathode band.
- Packaging: 12mm tape per EIA STD RS-481.
- Weight: 0.06 gram, 0.0018 ounce

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| | | • | | | | | | |
|--|---------------|------|------|------|------|------|------|-------|
| Type Number | CSMA | | CSMA | | | | CSMA | Units |
| - ypo rtambol | 4001 | 4002 | 4003 | 4004 | 4005 | 4006 | 4007 | Omto |
| Maximum Recurrent Peak Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average | 1 | | | | | | Α | |
| Forward Rectified Current @TL=110°C | | | | | | | | ^ |
| Peak Forward Surge Current, 8.3ms Single | | | | | | | | |
| Half Sine-wave Superimposed on 30 | | | | | | | | Α |
| Rated Load(JEDEC method) | | | | | | | | |
| Maximum Instantaneous | | | | 1.1 | | | | V |
| Forward Voltage @ 1.0A | 1.1 | | | | | | V | |
| Maximum DC Reverse Current at | 5(@Ta=25°C) | | | | | uA | | |
| Rated DC Blocking Voltage | 50(@Ta=125°C) | | | | | | | |
| Maximum Reverse Recovery Time (Note 1) | 1.8 | | | | | | uS | |
| Typical Junction Capacitance (Note 2) | | 12 | | | | | pF | |
| Operating Temperature Range Tj -55 to +150 | | | | | | • | °C | |
| Storage Temperature Range Tstg -55 to +150 | | | | | | | | °C |
| | | | | | | | | |

Note1: Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

Note2: Measured at 1 MHz and Applied VR=4.0Volts

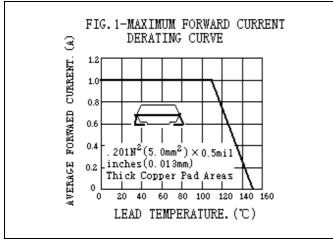


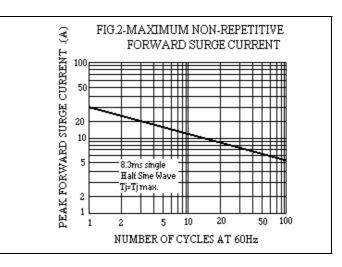
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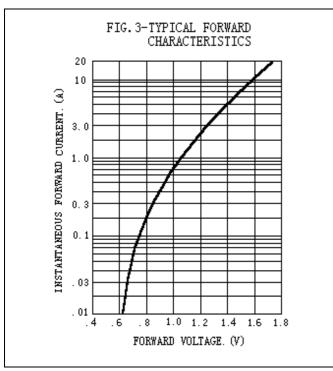
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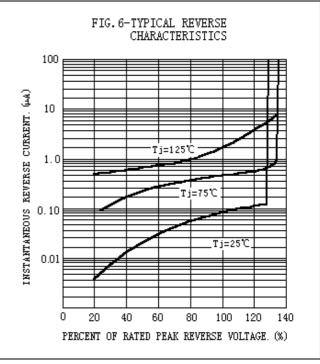
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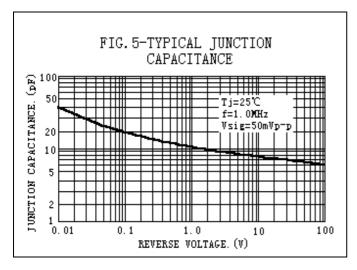
Characteristic Curves











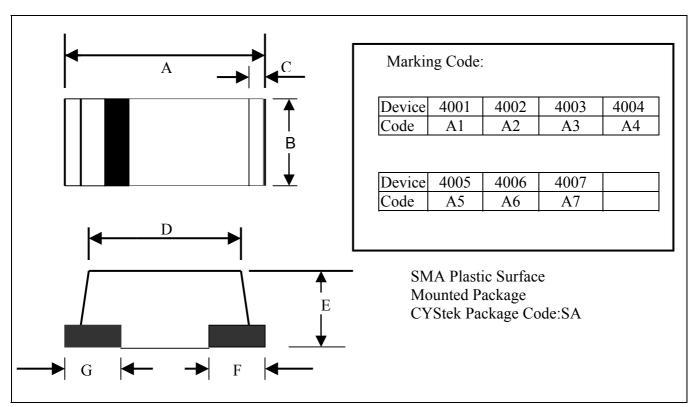


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SMA/DO-214AC Dimension



*:Typical

| : Typical | | | | | | | | | | |
|-----------|--------|--------|-------------|------|------|-----------|-------|-------------|------|--|
| DIM | Inches | | Millimeters | | DIM | Incl | hes | Millimeters | | |
| | Min. | Max. | Min. | Max. | וווט | Min. | Max. | Min. | Max. | |
| Α | 0.177 | 0.185 | 4.4 | 4.8 | Е | 0.060 | 0.067 | 1.5 | 1.7 | |
| В | 0.094 | 0.110 | 2.4 | 2.8 | F | 0.04(typ) | | 1.0(typ) | | |
| С | 0.012 | 2(typ) | 0.3(| typ) | G | 0.04(typ) | | 1.0(typ) | | |
| D | 0.150 | 0.165 | 3.8 | 4.2 | - | - | - | - | - | |

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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